

#### Features

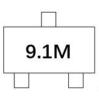
- Stand-off voltage:6V
- Transient protection for each line according to IEC61000-4-2(ESD): ±30kV (contact) IEC61000-4-5(surge): 1.7A (10/1000µs)
- Low leakage current:
- Ultra low clamping voltage
- Compliant

#### Applications

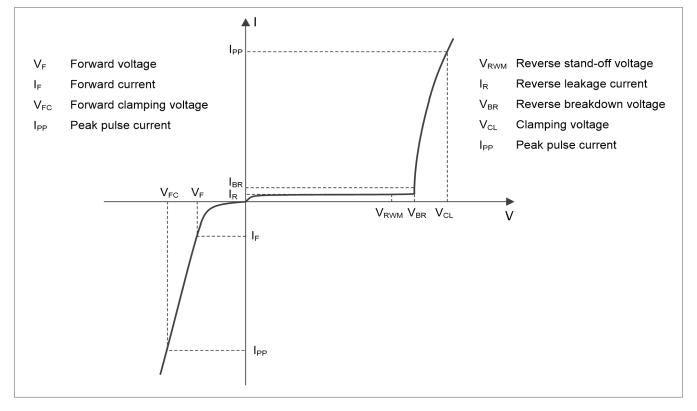
- Cellular Handsets and Accessories
- Notebooks and Handhelds
- Portable Instrumentation
- Set Top Box
- Industrial Controls
- Server and Desktop PC

## **Mechanical Data**

- Package: SOT-23
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound
- Moisture Sensitivity: Level 1 per J-STD-020
- Marking Information: See Below



## ■Definitions of electrical characteristics





#### Maximum Ratings

PARAMETER	SYMBOL	LIMITS	UNIT	
Peak pulse power (tp = 10/1000µs)	P <sub>pk</sub>	23.8	W	
Peak pulse current (tp = 10/1000µs)	Ірр	1.4	А	
ESD according to IEC61000-4-2 air discharge	M	±30	KV	
ESD according to IEC61000-4-2 contact discharge	V <sub>ESD</sub>	±30	κν	
Junction temperature	TJ	-55~150	°C	
Storage temperature	T <sub>STG</sub>	-55~150	°C	

## ■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	Symbol	UNIT	Conditions	Min	Тур	Max
Reverse maximum working voltage	V <sub>RWM</sub>	V				6
Reverse leakage current	I <sub>R</sub>	uA	V <sub>RWM</sub> = 6V			0.3
Reverse breakdown voltage	V <sub>BR</sub>	V	I <sub>BR</sub> = 1mA	8.65		9.56
Clamping voltage <sup>2)</sup>	VcL	V	I <sub>PP</sub> = 1.7A, t <sub>p</sub> = 10/1000μs			14
Junction Capacitance	CJ	pF	VR=0V,f=1MHz		185	

Notes:

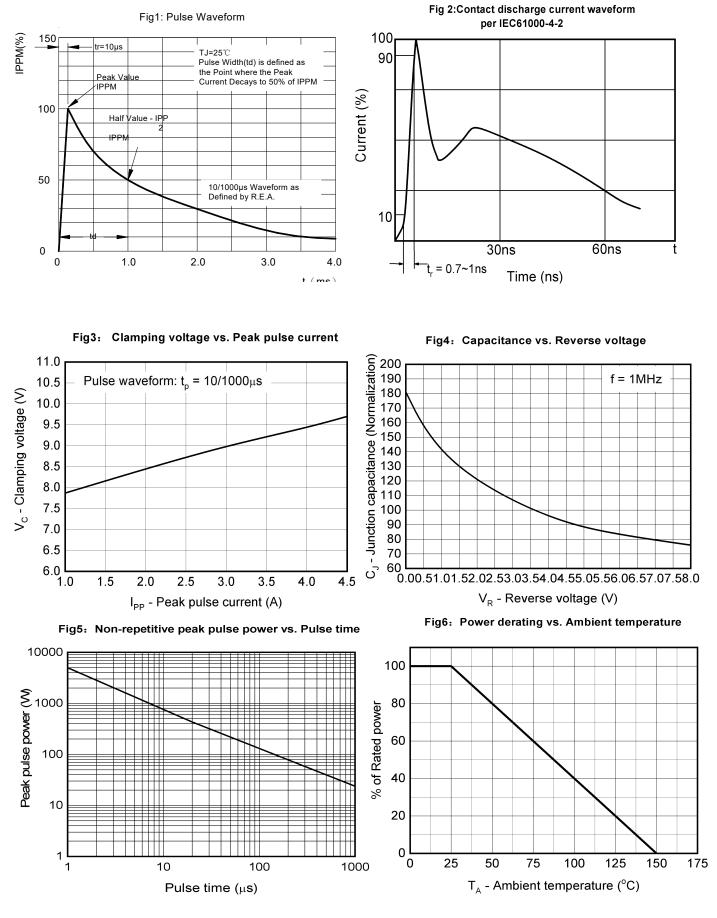
(1). TLP parameter:  $Z_0 = 50\Omega$ ,  $t_p = 100$  ns,  $t_r = 2$  ns, averaging window from 60 ns to 80 ns.  $R_{DYN}$  is calculated from 4A to 16A. (2). Non-repetitive current pulse, according to IEC61000-4-5.

## ■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(mg)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MMBZ9V1C	F2	Approximate 10	3000	30000	120000	7" reel

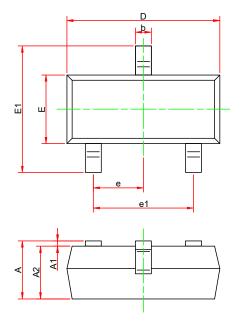


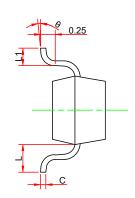
## Characteristics (Typical)





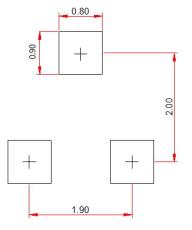
## Outline Dimensions





Symbol	Dimensions in millimeters				
Symbol	Min.	Тур.	Max.		
А	0.900	-	1.150		
A1	0.000	-	0.100		
A2	0.900	-	1.050		
b	0.300	-	0.500		
с	0.100	-	0.200		
D	2.800	-	3.000		
E	1.200	-	1.400		
E1	2.250	-	2.550		
е	0.950TYP				
e1	1.800	-	2.000		
L	0.550REF				
L1	0.300	-	0.500		
θ	0°	-	8°		

Soldering Footprint



#### Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.



# MMBZ9V1C

#### Disclaimer

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